*ELECTROCALLY CONDUCTIVE EPOXY AND POLYIMIDE RESINS, ONE-COMPONENT**

REF	CURING SCHEDULE Recommended	POT LIFE	VISCOSITY	Tg	DEGRADATION	FILLER	THERMAL EXPANSION		RESISTIVITY	COMMENTS
							BEFORE TG	AFTER TG		
E207-1	1 at 7 days at 25°C	4 h at 25°C	3,5 Pa.s	30-60°C	390-400°C	74%	50-60.10^{-6}/°C	120-140.10^{-6}/°C	<0,2 mΩ.cm	Silver conductive adhesive which can be cure at low temperature - Smart cards
E208	1 min at 150°C	6 h at 25°C	5,5 Pa.s	70-90°C	390-400°C	74%	40-50.10^{-6}/°C	110-120.10^{-6}/°C	<0,3 mΩ.cm	Smart cards - Sticking leds onto a flexible keyboard - Fast curing
E208FV	1 min at 150°C	8 h at 25°C	12,5 Pa.s	70-90°C	390-400°C	75%	40-50.10^{-6}/°C	110-120.10^{-6}/°C	<0,3 mΩ.cm	liquid resin - Smart cards, Flexible keyboard
E209	30 min at 150°C	3 months at 25°C	10 Pa.s	70-90°C	430-450°C	60%	40-50.10^{-6}/°C	90-100.10^{-6}/°C	<0,3 mΩ.cm	Good adhesion on tin/lead solder
E211	10 min at 150°C	7 days at 25°C	3 Pa.s	70-90°C	420-440°C	75%	40-50.10^{-6}/°C	100-130.10^{-6}/°C	<0,2 mΩ.cm	Tantalum capacitor - Pot life > at 7 days
E211FV	1 min at 150°C	18 h at 25°C	10 Pa.s	70-90°C	390-400°C	75%	40-50.10^{-6}/°C	110-120.10^{-6}/°C	<0,3 mΩ.cm	More reactive than E211
E211HV	1 min at 150°C	21 h at 25°C	13 Pa.s	70-90°C	390-400°C	75%	40-50.10^{-6}/°C	110-120.10^{-6}/°C	<0,3 mΩ.cm	More reactive than E211 - Pot life > 20 h
E213LF	5 min at 150°C	2 days at 25°C	15 Pa.s	70-80°C	390-410°C		40-50.10^{-6}/°C		<0,3 mΩ.cm	Perfectly adapted for the lead free solder resist - Tanatalum capacitor
E214	5 min at 150°C	24 h at 25°C	25 Pa.s	70-90°C	> 350°C	75%		90-100.10^{-6}/°C	<0,3 mΩ.cm	Correspond to the two component resin E203
E214SC	2 at 3 days at 20°C	8 h at 25°C	25 Pa.s	40-50°C	> 350°C		40-50.10^{-6}/°C	90-100.10^{-6}/°C	<0,3 mΩ.cm	Curing at room temperature
E216HV	10 min at 150°C	7 days at 25°C	15 Pa.s	70-100°C	420-440°C	79%	40-50.10^{-6}/°C	100-130.10^{-6}/°C	<0,3 mΩ.cm	sticking of large-sized components on lead frames
E216LF	1 h at 150°C	5 days at 25°C	25 Pa.s	50-80°C	380-410°C		35-45.10^{-6}/°C	90-100.10^{-6}/°C	<0,3 mΩ.cm	Perfectly adapted for the lead free solder resist
E217	1 h at 150°C	7 days at 25°C	15 Pa.s	-35 à -25°C	> 350°C	80%		150-180.10^{-6}/°C	<15 mΩ.cm	high flexible conductive adhesive - For high frequency quartz cristals
E217LF	1 h at 150°C	5 days at 25°C	12,5 Pa.s	30-35°C	430°C		60-65.10^{-6}/°C		<1 mΩ.cm	Perfectly adapted for the lead free solder resist - Sticking large size chips
E217SC	3 min at 150°C	2 days at 25°C	15 Pa.s	< -30°C	325°C			140.10^{-6}/°C	<5 mΩ.cm	Tantalum capacitor
E218	15 min at 170°C	24 h at 25°C	15 Pa.s	60-70°C	440°C		55-60.10^{-6}/°C	150-160.10^{-6}/°C	<1000 mΩ.cm	Good adhesion on lead frames or solder terminations
P200	1 h at 150°C + 1 h at 275°C	6 months at 25°C	10 Pa.s	190-210°C	> 550°C	64%	28-30.10^{-6}/°C	90-100.10-6/°C	< 0,5 mΩ.cm	Polyimide resin. High temperature
P202	1 h at 150°C + 1 h at 275°C	6 months at 25°C	100 Pa.s	190-210°C	> 550°C		28-30.10^{-6}/°C	90-100.10^{-6}/°C	<1 mΩ.cm	Polyimide resin. High temperature

The information in this sheet is based on data measurements which we believe to be correct. Epotecny, however, does not accept responsibility for the adaptation of this product to any particular use.

* for more precision on the technical properties, to refer to the individual data sheet.

Maj 27/10/2009

épotecny 9 rue Aristide Briand - 92300 Levallois Perret - France Tel : 33 (0)1-47-57-54-34 Fax : 33 (0)1-47-57-54-74 - e-mail : epotecny@epotecny.com - Website : www.epotecr